

Title (en)

METHOD FOR THINNING SOLID BODY LAYERS PROVIDED WITH COMPONENTS

Title (de)

VERFAHREN ZUM DÜNNEN VON MIT BAUTEILEN VERSEHENEN FESTKÖRPERSCHICHTEN

Title (fr)

PROCÉDÉ D'AMINCISSEMENT DE COUCHES DE SOLIDES POURVUES DE COMPOSANTS

Publication

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Application

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Abstract (en)

[origin: WO2018108938A1] The present invention relates to a method for separating at least one solid body layer (4) from at least one solid body (1). The method according to the invention includes the following steps: producing a plurality of modifications (9) by means of laser beams in the interior of the solid body (1) in order to form a separation plane (8); producing a composite structure by arranging or producing layers and/or components (150) on or above an initially exposed surface (5) of the solid body (1), wherein the exposed surface (5) is a part of the solid body layer (4) to be separated; introducing an external force into the solid body (1) in order to create stresses in the solid body (1), wherein the external force is so strong that the stresses cause a crack propagation along the separation plane (8), and wherein the modifications to form the separation plane (8) are produced before producing the composite structure.

IPC 8 full level

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